

AN 1996:39069 HCAPLUS  
DN 124:124164  
TI **Solders** and their preparation  
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PA Tanaka Electronics Ind, Japan  
SO Jpn. Kokai Tokkyo Koho, 5 pp.  
CODEN: JKXXAF  
DT Patent  
LA Japanese  
FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 07284983	A2	19951031	JP 1994-81853	19940420
PRAI	JP 1994-81853		19940420		

AB The **solders** are **Sn** alloys contg. 5-15 wt.% **Sb** and 2-15 wt.% **Ag**, or **Sn** alloys contg. 6-11 wt.% **Sb** and 6-12 wt.% **Ag**, and have tape- or wire-like shape and surface roughness (Ra) .ltoreq.10.mu.m. The **solders** are prepd. by cold forming. The **solders** have high ductility at 170.degree., and are suited for joining of members used at high temp., such as semiconductor device members.